

APPROVAL SHEET

MULTILAYER CERAMIC CAPACITOR Commercial Grade (IEC-60384 Qualified)

Approved by customer : (signing or stamping here)									

SAMWHA CAPACITOR CO., LTD.								
Writtern by Checked by Approved by								
21-85	7/-	gros-						

2023. 02. 10.

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Contents

Parts Numbering	
I. General Type	Page 3/16 ~ 6/16
II. Thin Layer Large-Capacitance Type	Page 7/16 ~ 9/16
III. High Voltage Type	Page 10/16 ~ 13/16

Enactment :	STANDARD	NO	SW - M - 04B	
March 27,1996	MULTILAYER CERAMIC CAPACITOR	Dogo	1 / 16	
,	Commercial Grade	Page		

1. General Article

Application Range

These specifications refer to the "Multilayer Ceramic Capacitors" mainly used to the computer equipment, communication equipment.

*Caution: Industrial equipment / For the high reliability equipment / LED equipment / Etc.

Please contact sales representatives or product engineers before using the products.

(For details, please refer Page 16)

2. General Code

(1) Type Designation

<u>CS</u>	<u> 1608</u>	<u>X7R</u>	<u>104</u>	<u>K</u>	<u>500</u>	<u>N</u>	<u>R</u>	<u>B</u>
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

- 1) Multilayer Ceramic Capacitor (Commercial Grade)
- 2) Size Code:

This is expressed in tens of a millimeter.

The first two digits are the length, The last two digits are width.

3) Temperature Coefficient Code

Classification	Code	Temperature Range	Capacitance Tolerance
Class I	C0G	-55 to +125℃	±30 ppm/℃
	X5R	-55 to +85℃	±15%
Class II	X7R	-55 to +125℃	±15%
	Y5V	-30 to +85℃	+22% ~ -82%

4) Capacitance Code(Pico farads):

The nominal Capacitance Value in pF is expressed by three digit numbers.

The first two digits represents significant figures and the last digit denotes the number of zero ex) 104 = 100000 pF

R denotes decimal

8R2 = 8.2 pF

5) Capacitance Tolerance Code

Code	Tolerance					
В	± 0.1 pF					
С	± 0.25 pF					
D	± 0.5 pF					
F	± 1.0 %					
G	± 2.0 %					
J	± 5 %					
K	± 10 %					

Code	Tolerance
М	± 20 %
Р	+ 100, -0%
Z	+ 80, -20%
Н	+ 0.25/-0 pF
I	+ 0/-0.25 pF
U	+ 5/-0 %
V	+ 0/-5 %

6) Voltage Code

_														
code	6R3	100	160	250	350	500	101	201	251	501	631	102	202	302
\/al	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC
Vol.	6.3V	10V	16V	25V	35V	50V	100V	200V	250V	500V	630V	1KV	2KV	3KV

7) Termination Code

ex) N: Ni-Sn (Nickel-Tin Plate)

A: Ag/Ni-Sn (Ag Epoxy/Nickel-Tin Plate) -> Soft Termination Type

8) Packing Code

ex) R: 7" Reel Type L: 13" Reel Type B: Bulk Type

9) Thickness option

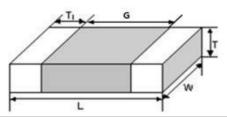
Thickness(mm)		Code	Thickne	Code	
t	Tol(±)	Oode	t	Tol(±)	
0.30	0.03	Blank	1.30	0.20	Е
0.50	0.05	Blank	1.35	0.20	Н
0.60	0.10	А	1.60	0.20	I
0.80	0.10	В	1.80	0.20	J
0.85	0.15	В	2.00	0.25	K
1.00	0.15	Е	2.50	0.25	L
1.10	0.15	Е	2.80	0.30	М
1.15	0.15	Е	3.20	0.30	N
1.25	0.15	E	5.00	0.40	0

3. Temperature Characteristics

See Page 6/16 (No.14)

4. Constructions and Dimensions

(I) Dimensions

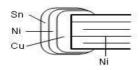


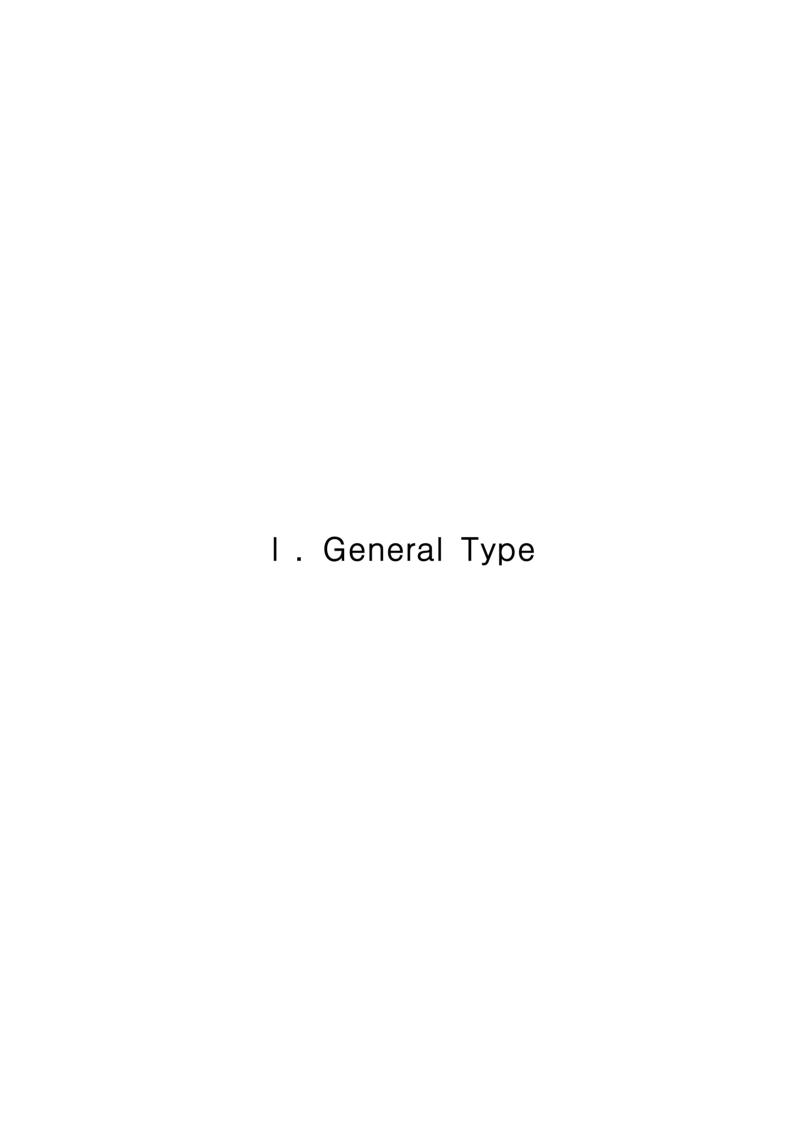
(Unit: mm)

	Dimension										
Code	Ler	ıgth	Wie	dth	T1 (main)	0()					
	L Tol(±) W		W	Tol(±)	T1(min)	G(min)					
0603	0.60	0.03	0.30	0.03	0.05	0.15					
1005	1.00	0.05	0.50	0.05	0.15	0.30					
1608	1.60	0.15	0.80	0.10	0.20	0.50					
2012	2.00	0.20	1.25	0.15	0.20	0.70					
3216	3.20	0.30	1.60	0.20	0.30	1.20					
3225	3.20	0.40	2.50	0.25	0.30	1.00					
4520	4.50	0.40	2.00	0.25	0.30	1.00					
4532	4.50	0.40	3.20	0.30	0.30	2.20					
5750	5.70	0.50	5.00	0.40	0.30	3.20					

*2012 Size ≥10 μ F \Rightarrow W : 1.25±0.20, T : 0.85±0.15 *3216 Size ≥47 μ F \Rightarrow W : 1.60±0.30, T : 1.60±0.30

(2) Construction of Termination





Specifications and Test Methods (General)

T			Tool Molliodo (C		cificati	on										
No.	lte	em	Class I	Class II					Test Methods and Conditions							
1	Operating Temperature Range	;	C0G :-55 to+125℃	X7R : -55 to +125℃ X5R : -55 to +85℃ Y5V : -30 to +85℃												
2	Insulation Resistance			than 10,000 MΩ or 500Ω.F (Whichever is smaller)						Applied the rated voltage for 2 minutes of charging, The charge/discharge current is less than 50mA.						
3	Voltage pro	of								COG: The rated voltage ×300% X7R, X5R, Y5V: " ×250% - Applied between the terminations for 1 to 5 seconds.						
										- The charge/discharge current is less than 50mA.						
4	Capacitance	9	within	the s	pecified	d tolera	ance			The capacitance/Q/D.F. should be measured at 25°C at the requency and voltage shown in the table.						
				Char.	50V min	25V	16V	10V	6.3V	Cap Testing frequency Voltage COG (C<1000pF) 1±0.1Mtz 0.5to5 Vrms						
	:		30pFmin : Q≥1,000(DF≤0.1%)	X7R X5R	≤2.5%/ ∗≤5%	≤3%/ *≤7%	≤3.5%/ *≤7%	≤5%/ *≤10%	≤5%/ *≤10%	COG (C≥1000pF) 1±0.1 kHz 1±0.2 Vrms X7R, X5R,Y5V (C≤10µF) 1±0.1 kHz 1±0.2 Vrms						
5	Dissipation	30pFmax : Q≥400+20C (DF≤1/ (400+20C)	: Q≥400+20C	7.0.1						X7R, X5R, Y5V						
									(DI ≥ I/ (400 200))		≤5%/ *≤9%	≦7%/ ∗≦9%	≦9%/ ∗≦12.5%	≦12.5%/ ∗≦15%	≦15%	Perform the initial measurement according to Note1 for Class II Measurement after test Take it out and set it for
										24±2 hours (Class I) or 24±2 hours (Class II) then measure						
6	Solderability		95% of the terminatio continuously.	5% of the terminations is to be soldered evenly and ontinuously.						*Pb-Free type Solder: 96.5Sn-3Ag-0.5Cu Solder temperature: 245±5°C Immersion time: 3±0.1sec *Pre-Heating: at 80~120°C for 10~30sec						
		Appearance	No defects v	vhich	may af	fect p	erforma	nce		Preheat the capacitor at 120 to						
		Capacitance change	within $\pm 2.5\%$ or $\pm 0.25 \mathrm{pF}$ (whichever is larger) $ \begin{array}{c} X7R, \ X5R \colon \leqq \ \pm 7.5\% \\ Y5V \ \colon \leqq \ \pm 20\% \\ \end{array} $						150°C for 1 minute. (Preheating for 3225,4520,4532 Step1:100°C to 120°C, 1min							
	to Factor		30 _p Fmin : Q≥1,000 (DF≤0.1%)	Char.	50V min	25V	16V	10V	6.3V	Step2:170°C to 200°C, 1min) Immerse the capacitor in a eutectic solder solution						
7			to	Factor Supremax	X7R X5R	≦2.5%/ ∗≦5%	≦3%/ *≦7%	≤3.5%/ ∗≤7%	≦5%/ *≦10%	≦5%/ *≦10%	·Soldering Temp:260 ±5°C ·Immersion Time:10 ±0.5 sec					
	Heat		: Q≥400+20C (DF≤1/(400+20C))	Y5V	Y5V ≤5%/ ≤7%/ ≤9%/ ≤12.5%/ ★≤9% ★≤12.5% ≤15%				≦15%	Initial measurement Perform the initial measurement according to Note1 for Class II						
I.R. More than 10,000MΩ or 500Ω.F (whichever is smaller)								Measurement after test Take it out and set it for 24±2 hours (Class I) or 24±2 hours (Class II) then measure								

				S	pecifica	ation									
No.	lt lt	em	Class I			Cla	ss II			Tes	t Metho	ds an	d Condi	itions	
		Appearance	No defects	whic	h may	affect	perform	ance			rm the fiv				
		Capacitance Change	Within ±2.5% or ±0.25pF (whichever is larger)	X7R, Y5V		Within ± Vithin ±2				following table. Step 1 2 3 4 Min. Max.					
				Char	50V min	25V	16V	10V	6.3V	Temp (℃)	operating temp. +0, -3	Room Temp	operating temp. +3, -0	Room Temp	
8	Rapid change of temperature	Dissipation Factor (or Q)	30pFmin : Q≥1,000 (DF≤0.1%)	X7R X5R	≦5%/ *≦7.5%	≦5%/ ∗≦10%	≦5%/ ∗≤10%	≦7.5%/ ∗≦12.5	≦7.5%/ *≦12.5%	Time (min) 30±3 2 to3 30±3		2 to3			
			30pFmax : Q≥400+20C (DF≤1/(400+20C))	Y5V	≦7.5%/ *≦12.5%	≦10%/ *≦12.5%	≦12.5%/ *≦15%	≦15%/ *≦20%	≦20%	Initial measurement Perform the initial measuremen according to Note1 for Class					
		I.R			than 10,000MΩ or 500Ω.F Whichever is smaller)						Measurement after test Perform the final measurement according to Note2				
		Appearance	No defects					ance		-Temperature : 40±2°C					
	Accelerated damp heat, steady state	Capacitance Change	Within ±7.5% or ±0.75pF (whichever is larger)	X7R, X5R : Within $\pm 12.5\%$ Y5V : Within $+30\%$, -40% (Y5V/1.0 μ F,2.2 μ F,4.7 μ F/10V) Within $\pm 30\%$ (others) Humidity : $90\sim95\%$ RH -Hour : $500+24/-0$ hrs ·Applied Voltage : Rated Voltage The charge/discharge current is											
9			30pFmin : Q≥200 (DF≤0.5%)	Cha	50V min	25V	16V	10V	6.3V	less	than 50m.	Α.	Current is)	
		Dissipation Factor(or Q)	30pFmax : Q≥100+10/3C	X7R X5R		≤5%/ *≤10%	≤5%/ *≤10%	≤7.5%/ *≤12.5	1	according to Note1 for Cl Measurement after test					
			DF≦1/(100+10/3C)	Y5V	≦7.5%/ *≦12.5%	≤10%/ *≤12.5%	≤12.5%/ *≤15%	≦15%/ *≦20%	≦20%					ont	
		I.R	Mo			lΩ or 25! s smalle				Perform the final measurement according to Note2				em	
		Appearance	No defects	•			,	ance		·Testin	g time :	1000+	48/-0 hrs		
		Capacitance Change	Within ±3% or ±0.3pF (whichever is larger)		: Within	Vithin ±1 ±30% (c +30%, - (cap	ap<1.0,	uF)		Rated	ed voltage d voltage erature :		:50V : ×2	200%	
			30pFmin : Q≥350 (DF≤0.3%)	Cha	50V	25V	16V	10V	6.3V) X	G, X7R - 5R, Y5V - charge/dis	→ 85±	3℃		
10	Endurance	Dissipation Factor	$ \begin{array}{c c} 10 pF \leq Cp \leq 30 pF \\ : Q \geq 275 + 5/2C \\ (DF \leq 1/(275 + 5/2C)) \end{array} $	X7R X5R		≦5%/ *≤10%	≤5%/ *≤10%	≤7.5%/ *≤12.5	1	·Initial	measure	ement	maaaura	mont	
		(or Q)	10pFmax : Q≥200+10C (DF≤1/(200+10C))	Y5V	≤7.5%/ *≤12.5%	≤10%/ *≤12.5%	≤12.5%/ *≤15%	≤15%/ *≤20%	≦20%	acco	Perform the initial measure according to Note1 for Cla				
		I.R				MΩ or 50 smaller		1	1	Measurement after test Perform the final measurement according to Note2				ent	

				Sn	ecifica	tion				
No	. It	em	Class I		23,,,,,		ıss II			Test Methods and Conditions
11	Substrate bending test	Capacitance	Printed circuit board under tes No cracking or ma Within ±5% or ±0.5pF	Probe to exert bending force Speed: 1.0mm/s *. Test condition - Bending limit: 1m - Pressurizing speed : 1mm/sec - Holding time: 5±1s 0.5pF X7R, X5R: Within ±10%						
		Change (whichever is larger) Y5V: Within ±30% Appearance No defects or abnormalities								
		Capacitance	Whin the specified to							- - - *After soldering and then let
12	Vibration	Q/DF	30pFmin : Q≥1,000 (DF≤0.1%) 30pFmax : Q≥400+20C (DF≤1/ (400+20C))	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		≤5%/ *≤10%	sit for 24±2hr(temperature compensating type), 24±2hr(high dielectric constant type) at room temperature. The capacitor should be subjected to a simple harmonic motion having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz, shall be traversed(from 10Hz to 55Hz then 10Hz again) in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3mutually perpendicular directions(total is 6hours).			
		Appearance	No defects v	which	may a	affect	oerform	ance		
		Capacitance Change	within ±5% or ±0.5pF (Whichever is larger)		, X5R: : Within		±12.5%	•		·Temperature : 40±2℃ ·Humidity : 90~95%RH
			30pF min : Q≥350 (DF≤0.3%)	Char	50V min	25V	16V	10V	6.3V	Hour: 500+24/-0 hrs
13	Damp heat, steady state	Dissipation (or Q)	10pF≤Cp≤30pF : Q≥275+5/2C (DF≤1/(275+5/2C))	X7R X5R	≤5%/ *≤7.5%	≤5%/ *≤10%	≤5%/ *≤10%	≦7.5%/ ∗≦12.5	≦7.5%/ ∗≤12.5%	Initial measurement Perform the initial measurement according to Note1 for Class II
			10pFmax : Q≥200+10C (DF≤1/(200+10C))	Y5V ≤7.5%/ *≤12.5% ≤12.5% ≤12.5% ≤15%/ *≤15% ×≤20% ≤20%				Measurement after test Perform the final measurement		
		I.R.			ı 1,000 ıever is					according to Note2

				Spe	ecification	on							
No.	Iten	1	Cla	ss I		Cla	ass II			Test Methods and Conditions			
14	Temperature characteristic	Capacitance Change			Char.	Temp Range	Reference Temp.	Cap Change	(1)	The ter	ature Compensating Type n perature coefficient is		
	of capacitance				X7R	-55 to +125℃		Within ±15%		measure	ned using the capacitance ed in step 3 as a reference, cycling the temperature		
					X5R	-55 to +85℃	25℃	Within ±15%		sequentially from step 1 through 5,(COG: +25 to 125°C) the capacitance shall be with in the specified tolerance for the temperature coefficient. The capacitance drift is calculated			
					Y5V	-30 to +85℃		Within +22% -82%					
										the max	ing the difference between ximum measured values in 1, 3 and 5 by the cap. step 3		
												Step	Temperature(℃)
										1	25±2		
			Char. Temp							3	-55±3 25±2		
		Temperature	Range	e Coefficient						4	125±3(for C0G)		
		Coefficient	C0G -55 to	1 ±30 nnm/(: 1						5	25±2		
			+125%							The range change value over range sh	ectric Constant Type ges of capacitance compared with the 25°C er the temperature own in the table shall be ecified range.		

*Note1. Initial Measurement for Class II

Perform a heat treatment at 150+0,-10°C for one hour and then let sit for 24±2 hours at room temperature, then measure

*Note2. Measurement after test

Let sit for 24±2 hours at room temperature, then measurement

2.Class II

Perform a heat treatment at 150+0,-10℃ for one hour and then let sit for 24±2 hours at room temperature, then measure.

"Following the International standards, the title of each test item is subject to change."

II. Thin	Layer	Large-Capacitance	Type

SW - M - 04B 7 / 16

Specifications and Test Methods (Thin Layer Large-Capacitance Type)

No.	lte	em	Specification	Test Methods and Conditions					
1	Operating Temperature Range		X7R : -55 to +125°C X5R : -55 to +85°C Y5V : -30 to +85°C						
2	Insulation Resistance		50Ω·F min	·Applied the rated voltage for 2 minutes of charging, The charge/discharge current is less than 50mA.					
3	Voltage proc	of	No defects or abnormalities	X7R, X5R, Y5V: The rated voltage × 250% - Applied between the terminations for 1 to 5 seconds. - The charge/discharge current is less than 50mA.					
4	Capacitance		within the specified tolerance	The capacitance/D.F. should be measured at 25°C at the					
5	Dissipation Factor		Dissipation Factor X7R, X5R: 12.5%max *3216 Size 100 _µ F: 15%max Y5V: 20%max			frequency and voltage shown in the table. Capacitance Frequency Voltage C≤10 L= 1 ± 0.1kHz 0.5~1.0Vrms C>10 L= 120 ± 24Hz 0.5±0.1Vrms Initial measurement Perform the initial measurement according to Note1 for Class II Measurement after test Take it out and set it for 24±2 hours (Class II) then measure			
6	Solderability		95% of the terminations is to be soldered evenly and continuously.	*Pb-Free type Solder: 96.5Sn-3Ag-0.5Cu Solder temperature: 245±5°C Immersion time: 3±0.1sec *Pre-Heating: at 80~120°C for 10~30sec					
		Appearance Capacitance change	No defects which may affect performance X7R, X5R: Within±7.5% Y5V: Within±20%	Preheat the capacitor at 120 to 150°C for 1 minute. (Preheating for 3225,4520,4532 Step1:100°C to 120°C, 1min Step2:170°C to 200°C, 1min Immerse the capacitor in a eutectic solder solution at					
7	Resistance to Soldering Heat	Dissipation Factor	X7R, X5R : 12.5%max *3216 Size 100 _{\(\rho\)} F : 15%max Y5V : 20%max	-260±5℃ for 10±0.5 seconds. Initial measurement Perform the initial measurement according to Note1 for					
		I.R.	50Ω·F min	Class II ·Measurement after test Let sit at room temperature for 24±2 hours,then measure.					
		Appearance	No defects which may affect performance	Perform the five cycles according to the four heat treatments listed in the following table.					
		Capacitance Change	X7R, X5R: Within ±7.5% Y5V: Within ±20%	Step 1 2 3 4 Min. Max. Temp operating Room operating Room					
8	Rapid change of temperature	Dissipation Factor	X7R, X5R: 12.5%max *3216 Size 100 _{\(\rho\)} F: 15%max Y5V: 20%max	(°C) temp. Temp temp. Temp +0/-3 +3/-0 Time 30±3 2 to3 30±3 2 to3					
	·	I.R	50Ω·F min	Initial measurement Perform the initial measurement according to Note1 for Class II Measurement after test Perform the final measurement according to Note2					

No.	Ito	em	Specification	Test Methods and Conditions
		Appearance	No defects which may affect performance	Apply 4500/ of the color by the color 4000 40 / 0
		Capacitance Change	X7R, X5R: Within ±12.5% Y5V: Within ±30%	Apply 150% of the rated voltage for 1000+48/-0 hrs at the maximum operating temperature ±3°C. The charge/discharge current is less than 50mA.
9	Endurance	Dissipation Factor	X7R, X5R : 20%max *3216 Size 100 _{\(\nu\)} F : 30%max Y5V : 40%max	-Initial measurement Perform the initial measurement according to Note1 for Class II
		I.R	12.5Ω·F min	Measurement after test Perform the final measurement according to Note2
10	Substrate bending test	Capacitance Change	Support Solder Chip Printed circuit board before testing 45±2 45±2 45±2 1.60±0.20 m or 0.80±0.10 m Printed circuit board under test Speed: 1.0 mm/s Speed: 1.0 mm/s 1.0 m Speed: 1.0 m Spee	·Substrate material : Glass EPOXY Board. ·Thickness : 1.6mm 0.8mm(0603/1005size) *. Test condition - Bending limit: 1mm - Pressurizing speed: 1mm/sec - Holding time: 5±1sec
			No defects or abnormalities	After soldering and then let sit for 24±2hr at room temperature.
		Capacitance	Whin the specified tolerance	The capacitor should be subjected to a simple
11	Vibration	Dissipation Factor	X7R, X5R : 12.5%max *3216 Size 100 _{\(\rho\)} F : 15%max Y5V : 20%max	harmonic motion having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz, shall be traversed(from 10Hz to 55Hz then 10Hz again) in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3mutually perpendicular directions(total is 6hours).
		Appearance	No defects which may affect performance	Apply the rated voltage at 40±2°C and
		Capacitance Change	X7R, X5R: Within ±12.5% Y5V : Within ±30%	90 to 95%RH for 500+24/-0 hrs. The charge/discharge current is less than 50mA.
12	Accelerated damp heat, steady state	Dissipation Factor	X7R, X5R: 20%max *3216 Size 100µF: 30%max Y5V: 40%max	Initial measurement Perform the initial measurement according to Note1 for Class II Measurement after test
		I.R.	12.5Ω·F min	Perform the final measurement according to Note2

No.	Item		Sp	ecification			Test Methods and Conditions
13	Temperature characteristic of capacitance	Char. X5R X7R Y5V	Temp. Range -55 to +85℃ -55 to +125℃ -30 to +85℃	Reference Temp. 25℃ 25℃ 25℃	Within	Change ±15% ±15% +22/-82%	The capacitance change should be measured after 5 min. at each specified temperature stage. The ranges of capacitance change compared with the 25°C value over the temperature ranges shown in the table should be within the specified ranges.

*Note1. Initial Measurement for Class II

Perform a heat treatment at 150+0,-10°C for one hour and then let sit for 24±2 hours at room temperature, then measure

*Note2. Measurement after test

Class I

Perform a heat treatment at 150+0,-10°C for one hour and then let sit for 24±2 hours at room temperature, then measure.

[&]quot;Following the International standards, the title of each test item is subject to change."

III. High Voltage Type

Specifications and Test Methods (High voltage type)

		Spe	ecification					
No.	Item	Class I	Class II		Test	Methods	and Condition	S
1	Operating Temperature Range	C0G :-55 to+125℃	X7R : −55 to +125°C					
2	Dimensions	Within the specified dimer	sion	Using	calipers			
				betwee		ions, provi	when voltage in tab ded the charge/disc Test voltage	
3	Voltage proof	No defects or abnormali	ties	C0G X7R	DC100V~630 DC1kV, DC2k DC3kV, DC3. DC100V~630 DC1kV	V 15kV 120%	6 of the rated voltage 6 of the rated voltage 6 of the rated voltage	e 1to5 sec
				A/n	DC2kV DC3kV	120%	of the rated voltag	e
4	Insulation Resistance	-DC100V~1KV :C≥0.01μF:More than 100MΩ·μF 10,000 MΩ :C<0.01μF:More than 10,000MΩ -DC2~3KV:More than6,000 MΩ			nutes of cha I voltage ≥[arging. OC500V:	Applied the rated The insulation resis	tance should
5	Capacitance	within the	specified tolerance	Cap	Testing f	requency	Testing Voltage	Measure temperature
		COG Char. :		COG 1±0.2M½(C<1000pF) 1±0.1½(C≥1000pF) AC 1±0.2Vrm			AC 1±0.2Vrms	25℃
6	Dissipation Factor	30pFmin : Q≥1,000(DF≤0.1%) 30pFmax : Q≥400+20C (DF≤1/ (400+20C))	2.5% max	. Initial measurement Perform the initial measurement according to Note1 for Class II . Measurement after test Take it out and set it for 24±2 hours (Class I) or 24±2 hours (Class II) then measure				
7	Temperature characteristic of capacitance	Temp. Coefficient COG char.: D±30ppm/℃ (Temp. Range: -55to+125℃) Cap. Change within ±15% (Temp. Range: -55 to +125℃)		X7R: 25°Cva-Pretri Perfo	itance measu cycling the the first the capa capace for the test of	red in ste emperature citance sh mperature f capacita e within th eatment at in let sit fo	Temperature(℃) 25±2 -55±3 25±2 125±3 (for COG) 25±2 nce change compane specified range. 150 -10, +0℃ for 24±2hrs.(Class	step 1 specified ared with the

			Specifi	cation	
No.	lte	em	Class I	Class II	Test Methods and Conditions
8	Adhesive Strength of Termination		No removal of the terminations occur	s or other defect should	Solder the capacitor to the testing jig(glass epoxy board) shown in Fig. 1 using a eutectic solder. Then apply 10N force in the direction of the arrow. The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. 10N(5N:Size 1.6×0.8mm only), 10±1s Speed: 1.0mm/s Glass Epoxy Board
		Appearance	No defects or abnormalities	3	
		Capacitance	Within the specified tolerance		The capacitor should be subjected to a simple harmonic
9	Vibration	Dissipation Factor(or Q)	COG Char.: 30pFmin : Q≥1,000(DF≤0.1%) 30pFmax : Q≥400+20C (DF≤1/ (400+20C))	2.5% max	motion having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz. The frequency range, from 10 to 55Hz and return to 10Hz, should be traversed in approximately 1 min. This motion should be applied for a period of 2hrs. in each 3mutually perpendicular directions(total of 6hrs.)
			No cracking defects should	occur.	Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 2 using a eutectic solder.
			44.5 100 + 1:1.6		Then apply a force in the direction shown in Fig. 3. The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock.
10	Substrate bending test		(mm) a 1.6×0.8 1.0 2.0×1.25 1.2 3.2×1.6 2.2 3.2×2.5 2.2 4.5×2.0 3.5	mension(mm) b	Pressurizing speed: 1.0mm/s R5 Pressurize Capacitance meter 45 45 (in mm) *. Test condition — Bending limit: 1 mm
		Capacitance Change	Within ±5% or ±0.5pF (whichever is larger)	Within ±10%	- Pressurizing speed : 1mm/sec - Holding time : 5±1sec
11	Solderability		95% of the terminations is and continuously.	to be soldered evenly	Immerse the capacitor in a solution of ethanol and rosin(25% rosin in weight proportion). Immerse in eutectic solder solution for 2±0.5 sec. at 245±5°C. Immersing speed: 25±2.5mm/s

	Item		Spo	ecification	
No.	lto	em	Class I	Class II	Test Methods and Conditions
		Appearance	No defects which may	affect performance	Preheat the capacitor at 120 to 150 ℃ * for 1 min.
		Capacitance change	within ±2.5%or ±0.25pF (whichever is larger)	within ±10%	Immerse the capacitor in eutectic solder solution at 260±5°C for 10±1 sec.
12	Resistance to Soldering Heat	Dissipation Factor (or Q)	COG Char.: 30pFmin : Q≥1,000(DF≤0.1%) 30pFmax : Q≥400+20C (DF≤1/ (400+20C))	2.5% max	-Immersing speed: 25±2.5mm/s Initial measurement Perform the initial measurement according to Note1 for Class II Measurement after test Let sit at room Temperature for
		I.R.	More than 10,000MΩ	-DC100V~1KV :C≥0.01 μF:More than 100MΩ·μF :C<0.01 μF:More than 10,000MΩ -DC2~3KV:More than1,000 MΩ	24±2hrs.(Class I), 24±2hrs.(Class II) then measure. *Preheating for more than 3.2×2.5mm Step Temperature Time 1 100°C to 120°C 1 min 2 170°C to 200°C 1 min
		Appearance	No defects which may	affect performance	Perform the 5 cycles according to the 4 heat treatments
		Capacitance Change	Within ±2.5%or ±0.25pF (whichever is larger)	within ±15%	listed in the following table.
10	Rapid 13 change of	Dissipation Factor (or Q)	COG Char.: 30pFmin : Q≥1,000(DF≤0.1%) 30pFmax	DC100V~1KV: 2.5% max	Step
13	temperature	(or Q)	: Q≥400+20C (DF≤1/ (400+20C))	DC2~3KV: 5%max	Initial measurement Perform the initial measurement according
		I.R	More than 10,000MQ	-DC100V~1KV :C≥0.01 µF:More than 100MQ·µF :C<0.01 µF:More than 10,000MQ -DC2~3KV:More than 3,000MQ	to Note1 for Class II ·Measurement after test Perform the final measurement according to Note2
		Appearance	No defects which may	affect performance	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1
		Capacitance Change	within ±5% or ±0.5pF (Whichever is larger)	Within ±15%	Let the capacitor sit at 40±2°C and relative humidity of 90 to 95% for 500+24/-0 hrs.
14	Damp heat, steady state	Dissipation Factor (or Q)	COG Char. : $C \ge 30 \text{pF} : Q \ge 350$ $C < 30 \text{pF} : Q \ge 275 + \frac{5}{2} \text{ C}$	5% max	Initial measurement Perform the initial measurement according to Note1 for Class II
		I.R	More than 1,000MΩ	-DC100V~1KV :C≥0.01 µF:More than 10MQ: µF :C<0.01 µF:More than 1,000MQ -DC2~3KV:More than 1,000MQ	Measurement after test Perform the final measurement according to Note2
		Appearance	No defects which may	affect performance	Apply the voltage in following table
		Capacitance Change	within ±3% or ±0.3pF (Whichever is larger)	DC100V,630V:Within ±15% DC1KV:Within ±20% DC2~3KV:Within ±20%	for 1,000+48/-0hrs. at maximum operating temperature ±3°C. The charge/discharge current is less than 50mA.
		Dissipation	COG Char. : C≥30pF : Q≥350	50/ 72.00	Operating temperature Rated voltage Test voltage range
		(or Q)	$C < 30 \text{pF} : Q \ge 275 + \frac{5}{2} \text{C}$	5% max	Rated voltage ≥DC1KV Rated voltage
15	Endurance				<dc1kv 120%="" fated="" of="" td="" the="" voltage<=""></dc1kv>
					DC100V~250V 150% of the rated voltage X7R DC500V~630V 120% of the rated voltage
		I.R. More than	More than 1,000MΩ	-DC100V~1KV :C≥0.01μF:More than 10MΩ·μF :C<0.01μF:More than 1,000MΩ -DC2~3KV:More than 2,000MΩ	Initial measurement Perform the initial measurement according to Note1 for Class II Measurement after test Perform the final measurement according to Note2

	Item			Specification	
No.			Class I	Class II	Test Methods and Conditions
		Appearance		No defects which may affect performance	Apply the rated voltage at 40±2°C and relative
	Humidity Load	Capacitance Change		Within ±15%	humidity of 90 to 95 for 500+24/-0 hrs. Initial measurement
16	(Application : DC250V	Dissipation (or Q)		5% max.	Perform the initial measurement according to Note1 for Class II
	item)	I.R.		C \geq 0.01 μ F:More than 10 $M\Omega \cdot \mu$ F C $<$ 0.01 μ F:More than 1,000 $M\Omega$	Measurement after test Perform the final measurement according to Note2

*Note1. Initial Measurement for Class II

Perform a heat treatment at 150+0,-10°C for one hour and then let sit for 24±2 hours at room temperature, then measure

*Note2. Measurement after test

1.Class I

Let sit for 24±2 hours at room temperature, then measurement

2.Class II

Perform a heat treatment at 150+0,-10°C for one hour and then let sit for 24±2 hours at room temperature, then measure.

[&]quot;Following the International standards, the title of each test item is subject to change."

5. Packing

- (1) Bulk packing
 - 1 1000 pcs per Polybag
 - 2 5 Polybags per Inner box
 - 3 10 Inner boxes per Out box
- (2) Reel Packing
 - ① 8~10 Reels per Inner box
 - 2 6 Inner boxes per Out box
- (3) Reel Dimensions



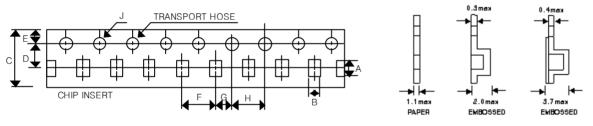


						(L	Jnit: mm)
MARK	SIZE	Α	В	С	D	Е	W
7 " RFFI	0603~3225	Φ178±2	Φ50Min	Ф13±0.5	Φ21±0.8	2±0.5	10±1.5
/ REEL	4520~4532	Ф180+0,-3	Ф60-0,+1	Ф13±0.2	Ф57-0+1	3±0.2	13±0.5
13 " REEL	1005~3225	Ф330±2	Ф70Min	Φ13±0.5	Φ21±0.8	2±0.5	10±1.5

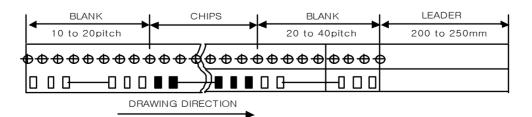
(4) Number of Package

TYPE	FIA CODE	7"	13"		
	EIA CODE	Qt/REEL	Qt/REEL		
CS0603	CC0201	15,000			
CS1005	CC0402	10,000	50,000		
CS1608	CC0603	4,000	15,000		
CS2012	CC0805	3,000 ~ 4,000	8,000 ~ 15,000		
CS3216	CC1206	2,000 ~ 4,000	6,000 ~ 10,000		
CS3225	CC1210	1,000 ~ 3,000	4,000 ~ 10,000		
CS4520	CC1808	1,500 ~ 3,000	_		
CS4532	CC1812	500 ~ 1,000	1,500 ~ 5,000		

(5) Tape Dimensions



TYPF	EIA CODE	Α	В	С	D	F	F	G	Н	.I
1111	LI/ CODE							<u> </u>	- ''	U
CS0603	CC0201	0.67±0.05	0.37±0.05	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.1	4.0±0.1	1.5±0.1
CS1005	CC0402	1.15±0.1	0.65±0.1	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.1	4.0±0.1	1.5±0.1
CS1608	CC0603	1.9±0.2	1.10±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS2012	CC0805	2.4±0.2	1.65±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS3216	CC1206	3.6±0.2	2.00±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS3225	CC1210	3.6±0.2	2.80±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS4520	CC1808	4.8±0.2	2.3±0.2	12.0±0.3	5.5±0.1	1.75±0.1	4.0±0.1 8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS4532	CC1812	4.9±0.2	3.6±0.2	12.0±0.3	5.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1



6. Caution

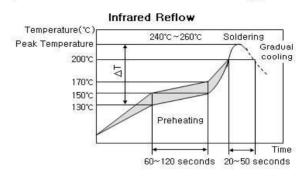
▶ Reflow Soldering

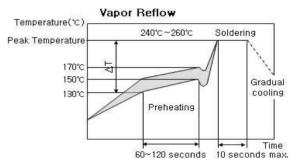
- 1. The sudden temperature change easily causes mechanical damages to ceramic components. Therefore, the preheating procedures should be required for the soldering of ceramic components.
- 2. Please refer to the recommended soldering profiles as shown in figures, and keep the temperature difference $(\triangle T)$ within the range recommended in Table 1.

Table 1

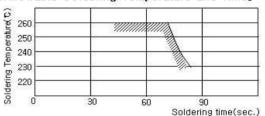
Size code	Temperature Difference		
0603, 1005, 1608, 2012, 3216	△T≤190°C		
3225size and over	△T≤130°C		

[Standard Conditions for Reflow Soldering]





[Allowable Soldering Temperature and Time]



In case of repeated soldering, the accumulated soldering time must be within the range shown above.

► Storage Condition

*When Solderability is considered. Capacitor are recommended to be used in 12 months

(1) Temperature: 25°C ± 10°C

(2) Relative Humidity: Below 70% RH

▶ The Regulation of Environmental Pollution Materials.

*Never use materials mentioned below in MLCC products regulated this document.

Pb, Cd, Hg, Cr⁺⁶, PBB(Polybromide biphenyl), PBDE(Polybrominated diphenyl ethers), asbestos.

* Note

(1) 'Aging'/'De-aging' Behavior of high dielectric MLCCs

(Typically represented by X7R, Y5V temperature characteristic of which main composition is BaTiO3)

'Aging' / 'De-aging' Behavior of high dielectric MLCCs Please note that high dielectric type dielectric Ceramic Capacitors have a "normal" 'aging' behavior / characteristic, that is; their capacitance value decreases with time from its value when it was first manufactured. From that date, the capacitance value begins to decrease at a logarithmic rate defined by:

$$C_t = C_{24} (1 - k \log 10 t)$$

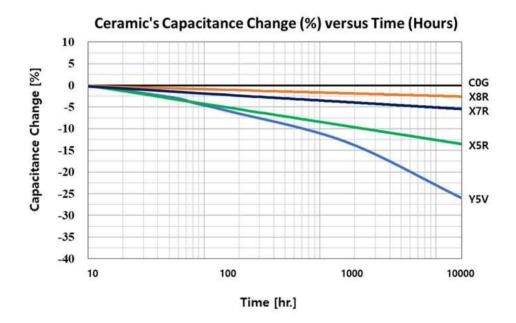
where:

Ct = Capacitance Value, t hours after the start of 'aging'

C₂₄ = Capacitance Value, 24 hours after its manufacture

k = aging constant (capacitance decrease per decade-hour)

t = time, in hours, from the start of 'aging'



The capacitance value can be restored (a.k.a. 'de-aged') by exposing the component to elevated temperatures approaching its Curie Temperature (approximately 120°C). This 'deaging' can occur during the component's solder-assembly onto the PCB, during life or temperature cycle testing., or by 'baking 'at 150°C for about 1 hour.

- (2) Please contact our sales representatives or product engineers before using the products in this catalog for the applications listed below, which require especially high reliability for the prevention of defects which might directly damage a third party's life, body or property, or when one of our products is intended for use in applications other than those specified in this catalog.
 - ①Aircraft equipment
- ②Aerospace equipment
- 3 Undersea equipment

- ©Transportation equipment (vehicles, trains, ships, etc.)
- Traffic signal equipment Spisaster prevention / crime prevention equipment